

REMARKS

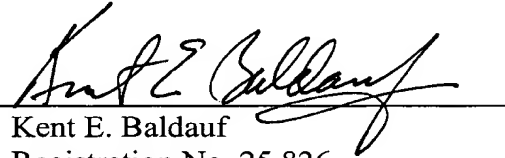
The specification has been amended to place the application in conformance with standard United States patent practice.

Examination and allowance of pending claims 1-3 are respectfully requested.

Respectfully submitted,

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## MARKED-UP AMENDED SPECIFICATION PARAGRAPH

### Page 1, title

[PROCESS FOR PRODUCING CARD]  
CARDS

PROCESS FOR PRODUCING

### Page 1, first complete paragraph

The present invention relates generally to a process for producing IC (integrated circuit) cards. More particularly, the present invention relates to a process for producing cards, which can avoid exposure, on the card surface, of unevennesses of components such as IC chips, capacitors and antenna coils mounted or formed on a mount substrate.

### Page 4, first section heading

[DISCLOSURE OF THE INVENTION]

SUMMARY OF THE INVENTION

### Page 6, first section heading

[BRIEF DESCRIPTION OF THE DRAWING]

BRIEF DESCRIPTION OF THE  
DRAWINGS

### Page 7, first section heading

[BEST MODE FOR CARRYING OUT THE INVENTION]

DETAILED  
DESCRIPTION OF THE INVENTION

### Page 9, second complete paragraph

Further, an adhesive 28, 30 in fluid condition [28, 30] is fed over respective surfaces 20A, 22A of the sheet members 20, 22 delivered from the sheet member supply rolls 16, 18 through adhesive supply means 32, 35 such as die coaters or T-dies.

[illegible]